



Material Content Data Sheet



Sales Product Name		TLE7182EM		Issued		27. September 2017		
MA#		MA000978514						
Package		PG-SSOP-24-4		Weight*		150.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.244	2.81	2.81	28132	28132
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8916	
wire	non noble metal	copper	7440-50-8	54.617	36.20	37.14	362014	371487
	noble metal	gold	7440-57-5	0.531	0.35	0.35	3519	3519
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1136
encapsulation	plastics	epoxy resin	-	7.886	5.23		52273	
	inorganic material	silicondioxide	60676-86-0	77.664	51.48	56.82	514773	568182
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19294	19294
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.295	0.20		1958	
	noble metal	silver	7440-22-4	0.886	0.59	0.79	5875	7833
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com